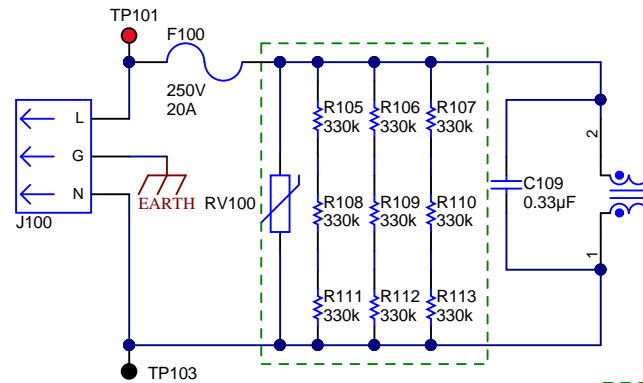


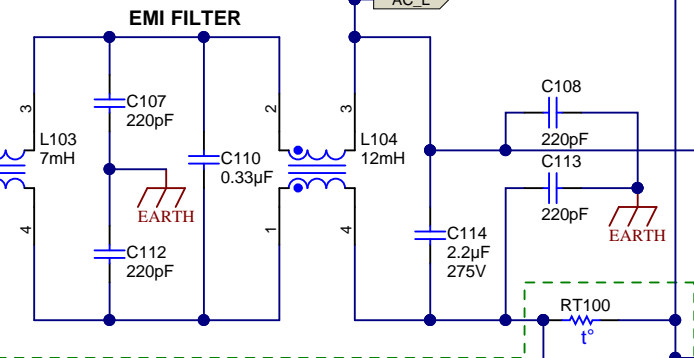
EMI and Power Stages

Safety Discharge and Lightning Protection.

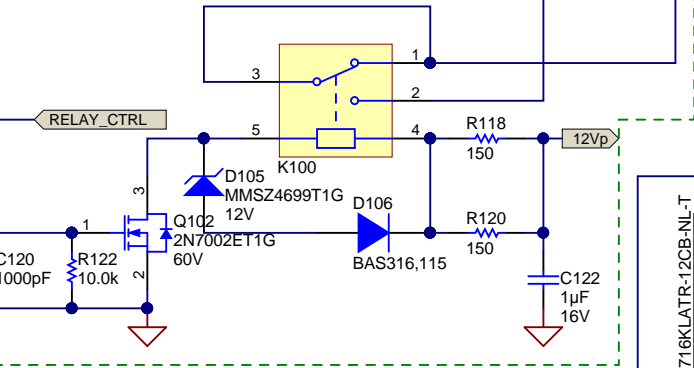


- Notes:**
1. Q100, Q101 lay flat to screw to bottom heatsink.
 2. Use Aavid MAX07NG Clip for Q100, Q101.
 3. With 0A, ACS716 output is Vcc/2.
 4. Work with PMP20396 Bias supply.
 5. Input/output connects TBD.

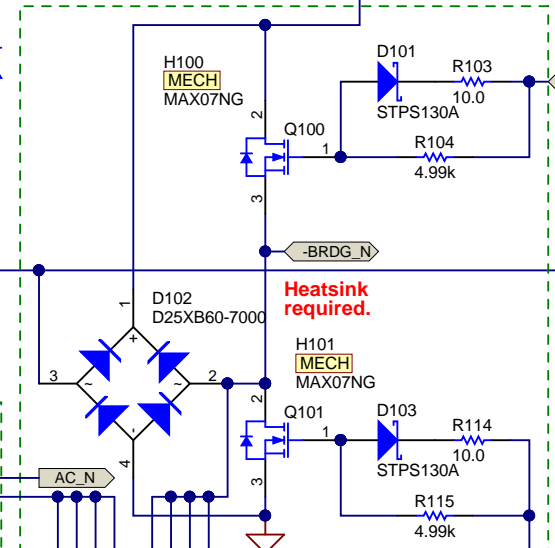
EMI FILTER



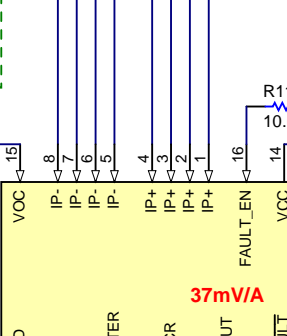
Inrush Current Limiting Circuit.



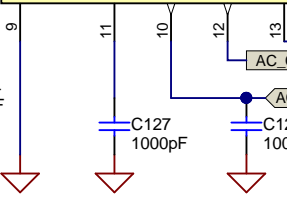
FET Paralleled Rectifier



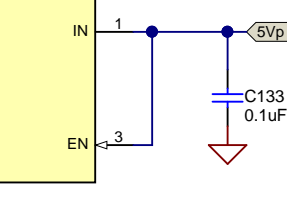
Heatsink required.



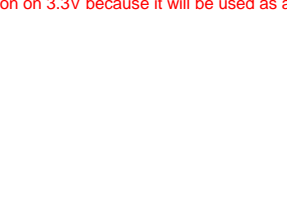
37mV/A



132mV/A



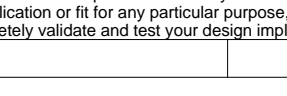
132mV/A



132mV/A



132mV/A



132mV/A

132mV/A

132mV/A

132mV/A

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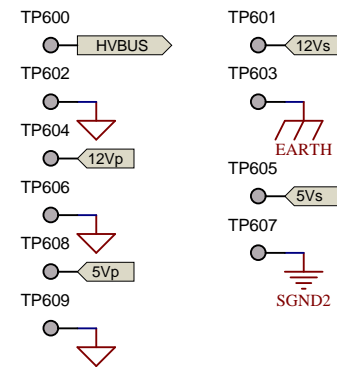
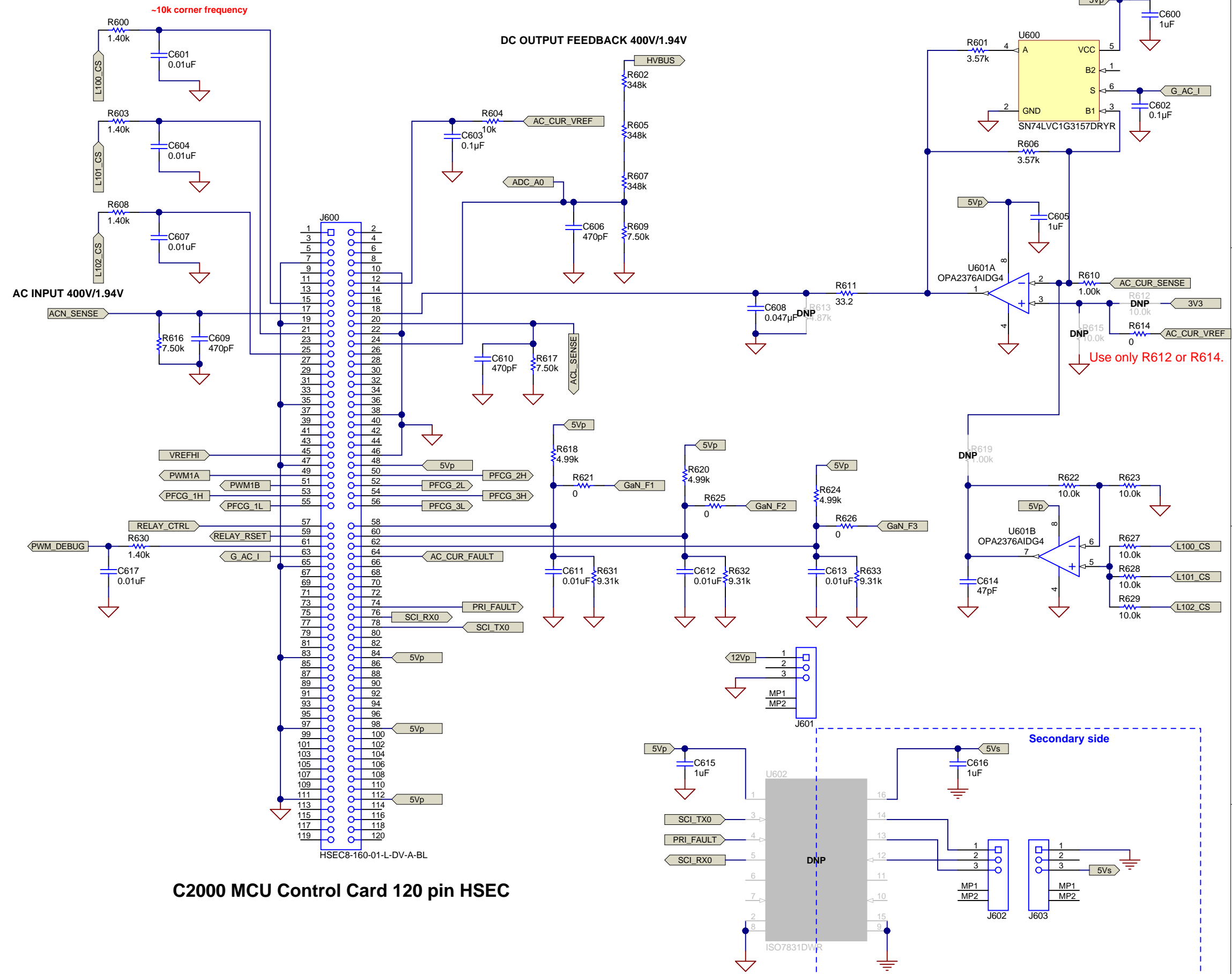
132mV/A

132mV/A

132mV/A

Notes:

1. C2000 connector pin definition is different from Samtec definition.



C2000 MCU Control Card 120 pin HSEC

Orderable: Not Applicable	Designed for: Public Release	Mod. Date: 10/31/2017
TID #: TIDM-1007	Project Title: Inteleaved 3.3kW TPBL PFC	
Number: TIDM-1007	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By:	File: TIDM-1007_Control.SchDoc	Size: B
Engineer: S Yu/Z Ye/ M Bhardwaj	Contact: http://www.ti.com/support	

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